

Ideal Diode V-Diode $^{\text{TM}}$ MF2003SV

Reverse connection protection and Reverse current prevention circuits

Input Voltage	DC12V	
Output Current	5A	

Substrate conditions

Board size	25mm×25mm		
Number of layers	2layers (double-sided)		
Copper foil thickness	35 um		
Substrate thickness	1.6 mm		
Material	Tg180 FR-4		

J572-1-en(2025.06)

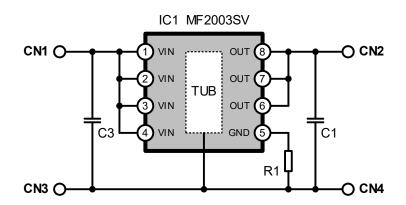


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Reference circuit diagram

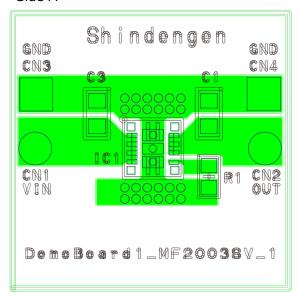


Bill Of Material

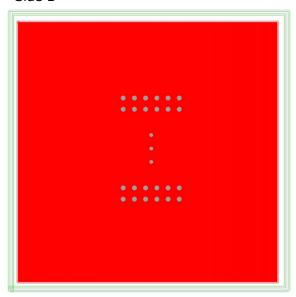
No.	Туре	Qt'y	Spec		Model Name	Vendor	Remarks
IC	Ideal Diode IC	1	-	-	MF2003SV	SHINDENGEN	-
C1	MLCC	1	50V	1uF	-	TDK	-
C3	MLCC	-	-	-	-	-	-
R1	Chip Resistor	1	1/8 W	10 kΩ	-	KOA	-

Board pattern

Side A

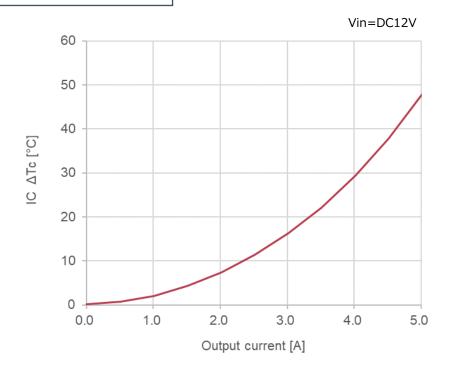


Side B

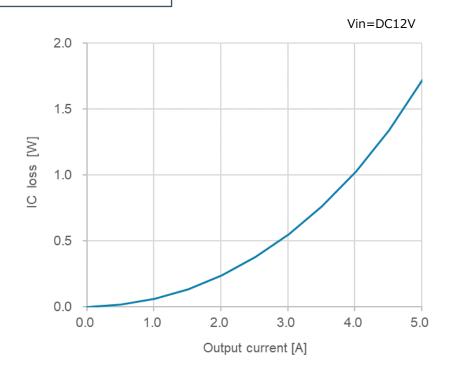




Temperature



IC loss





Operation waveform

Photo.1 Startup

Vin=12V Iout=5A

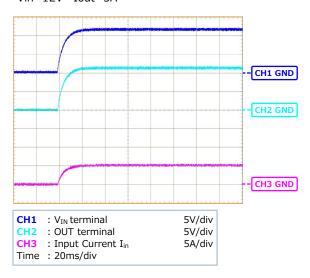


Photo.2 Shutdown

Vin=12V Iout=5A

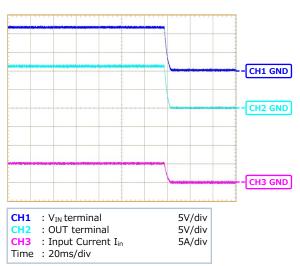


Photo.3 Input reverse connection

Vin=-12V Iout=0A Negative voltage applied

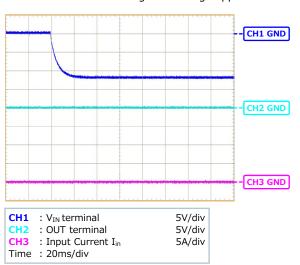


Photo.4 Reverse current blocking

Vin=12V→0V Iout=1A

